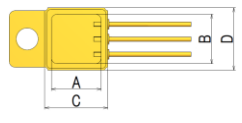
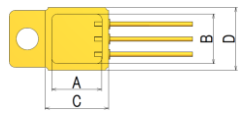
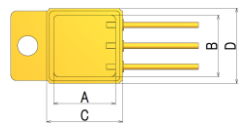
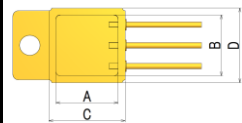
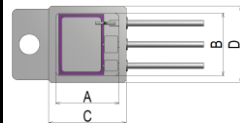
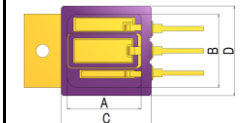
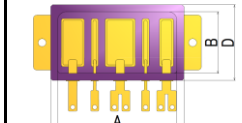


## KYOCERA TO CERAMIC PACKAGES (FOR ENGINEERING EVALUATION)

Unit : mm

No.	1	2	3	4	5	6	7
PACKAGE TYPE	TO-257 PKG	TO-257 PKG	TO-254 PKG	TO-254 PKG	TF-TO254 PKG	TF-TO3P PKG	TF-HB PKG
DRAWING NUMBER	PGMR-A6142	PGMR-A6141	PGMR-A6140	PGMR-A6139	GMR-A9455-A	SGMR-B4385	GMR-B1372
TOP VIEW							
CAVITY A x B	8.35 x 8.35	8.35 x 8.35	11.18 x 11.18	11.18 x 11.18	11.18 x 11.18	18.00 x 18.00	34.20 x 18.00
CERAMIC OVERALL C x D	10.55 x 10.55	10.55 x 10.55	13.72 x 13.72	13.72 x 13.72	13.72 x 13.72	22.00 x 22.00	38.20 x 22.00
TOTAL THICKNESS	5.77	5.27	6.94	6.44	6.49	5.70	6.75
SEAL RING	FeNiCo ALLOY	METALLIZATION	FeNiCo ALLOY	METALLIZATION	METALLIZATION	NO METALLIZATION	NO METALLIZATION
LEAD COUNT	3	3	3	3	3	3	5
LEAD MATERIAL	ALLOY 50 (Cu CORED)	ALLOY 50 (Cu CORED)	ALLOY 50 (Cu CORED)	ALLOY 50 (Cu CORED)	ALLOY 50 (Cu CORED)	O.F.H.C.	O.F.H.C.
HEAT SINK MATERIAL (THERMAL CONDUCTIVITY)	KYCM <sup>®</sup> (260W/mK)	KYCM <sup>®</sup> (260W/mK)	KYCM <sup>®</sup> (260W/mK)	KYCM <sup>®</sup> (260W/mK)	KYCM <sup>®</sup> (260W/mK)	Cu-W (175W/mK)	Cu-W (175W/mK)
MATCHING LID DRAWING NUMBER	PGMR-A9389 (METAL LID)	-	PGMR-A9388 (METAL LID)	SGMR-B3416 (METAL LID)	SGMR-B3416 (METAL LID)	-	-

Note 1 . KYCM is a registered trademark of KYOCERA Corporation in Japan.  
2 . TF-TO254 PKG, TF-TO3P PKG and TF-HB PKG: Courtesy of Osaka University